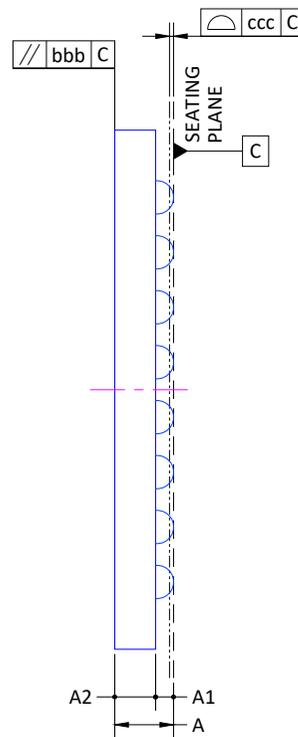
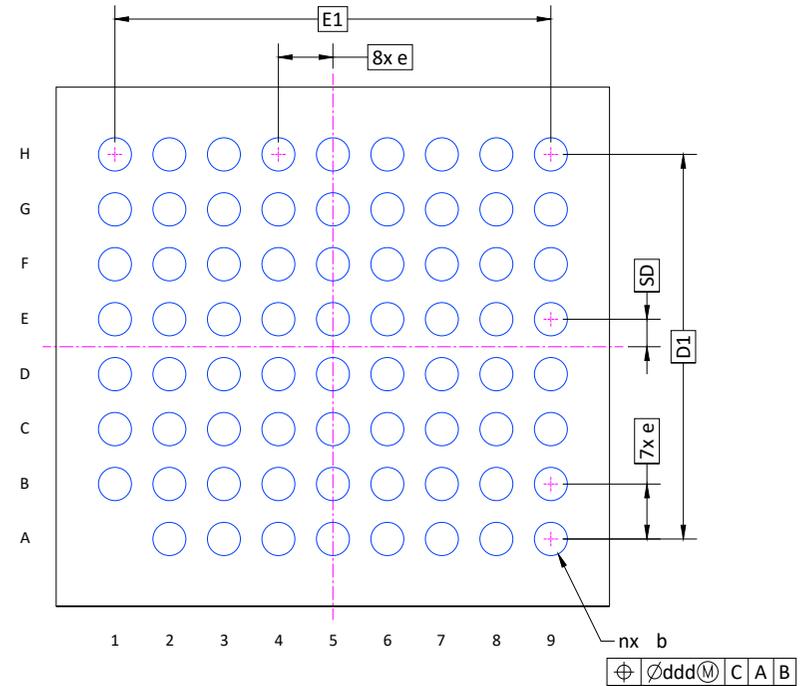


TOP VIEW



SIDE VIEW



BOTTOM VIEW

Control Dimensions are in Millimeter

| | Symbol | Common Dimensions | | |
|------------------------------|--------|-------------------|-------|--------|
| | | MIN. | NOM. | MAX |
| Total Thickness | A | 0.392 | 0.432 | 0.472 |
| Stand Off | A1 | 0.117 | 0.132 | 0.147 |
| Wafer Thickness | A2 | 0.275 | 0.300 | 0.325 |
| Body Size | Y D | 3.779 | | (Min.) |
| | X E | 4.061 | | (Min.) |
| Ball / Bump Pitch | Y SD | 0.200 | BSC | |
| | X SE | --- | BSC | |
| Edge Ball Center to Center | Y D1 | 2.80 | BSC | |
| | X E1 | 3.20 | BSC | |
| Pitch | e | 0.400 | BSC | |
| Ball Diameter (Size) | | 0.20 | | |
| Ball / Bump Width | b | 0.198 | 0.242 | 0.245 |
| Ball / Bump Count | n | 71 | | |
| Package Edge Tolerance | aaa | 0.03 | | |
| Wafer Flatness | bbb | 0.06 | | |
| Coplanarity | ccc | 0.03 | | |
| Ball / Bump Offset (Package) | ddd | 0.015 | | |